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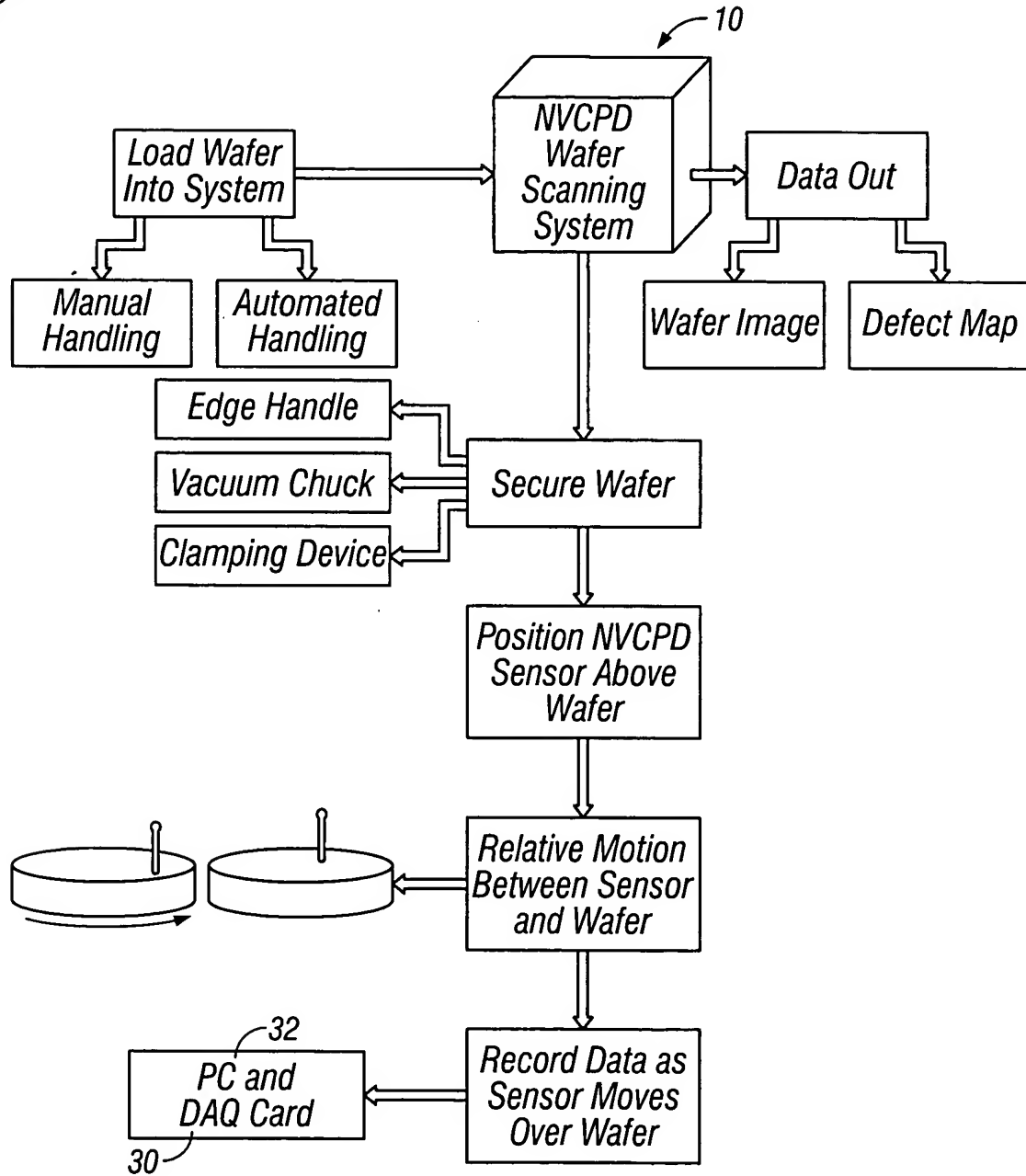


FIG. 1

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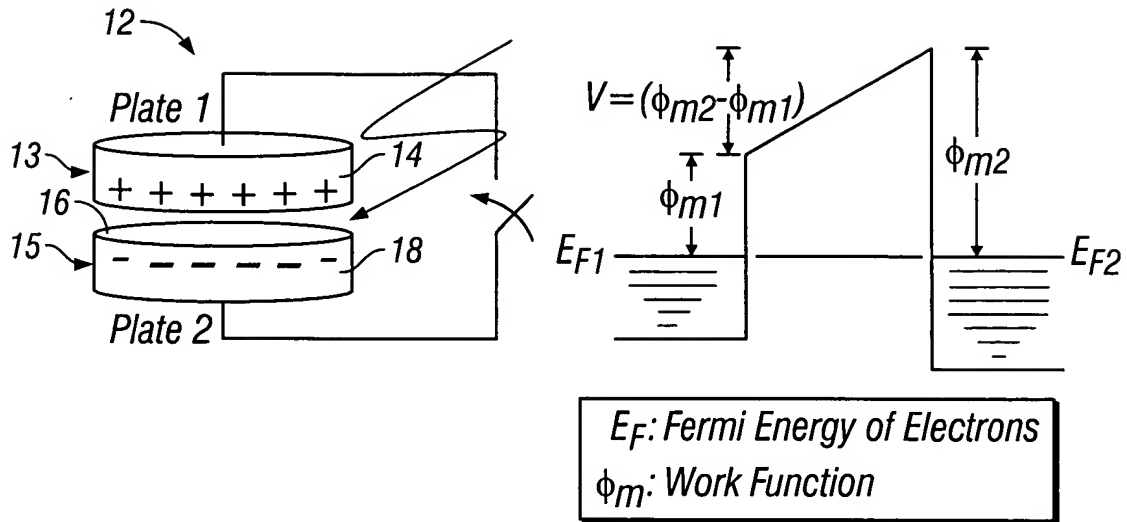


FIG. 2

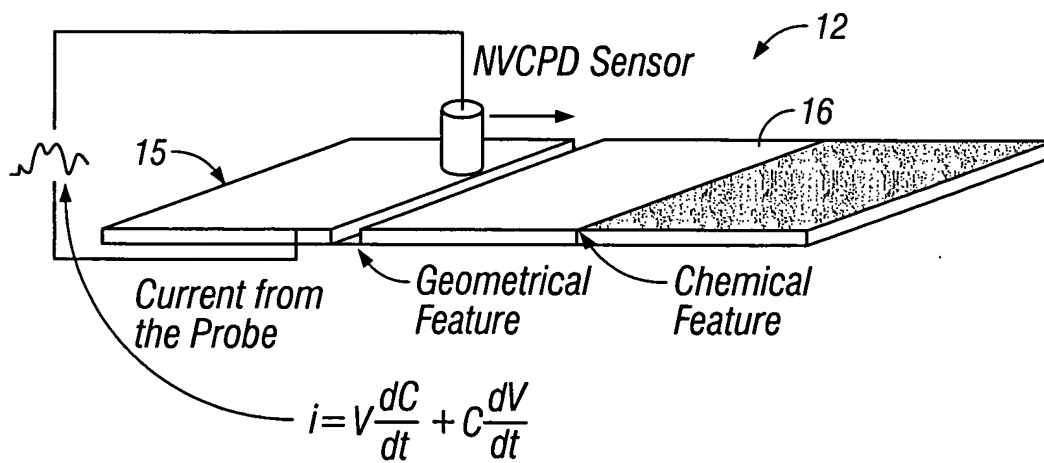


FIG. 3

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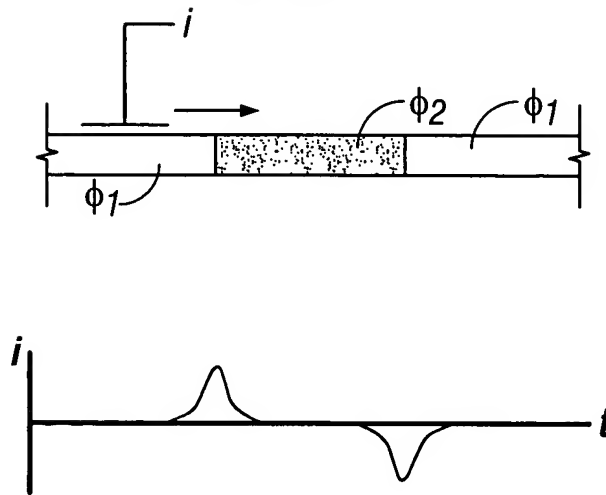


FIG. 4

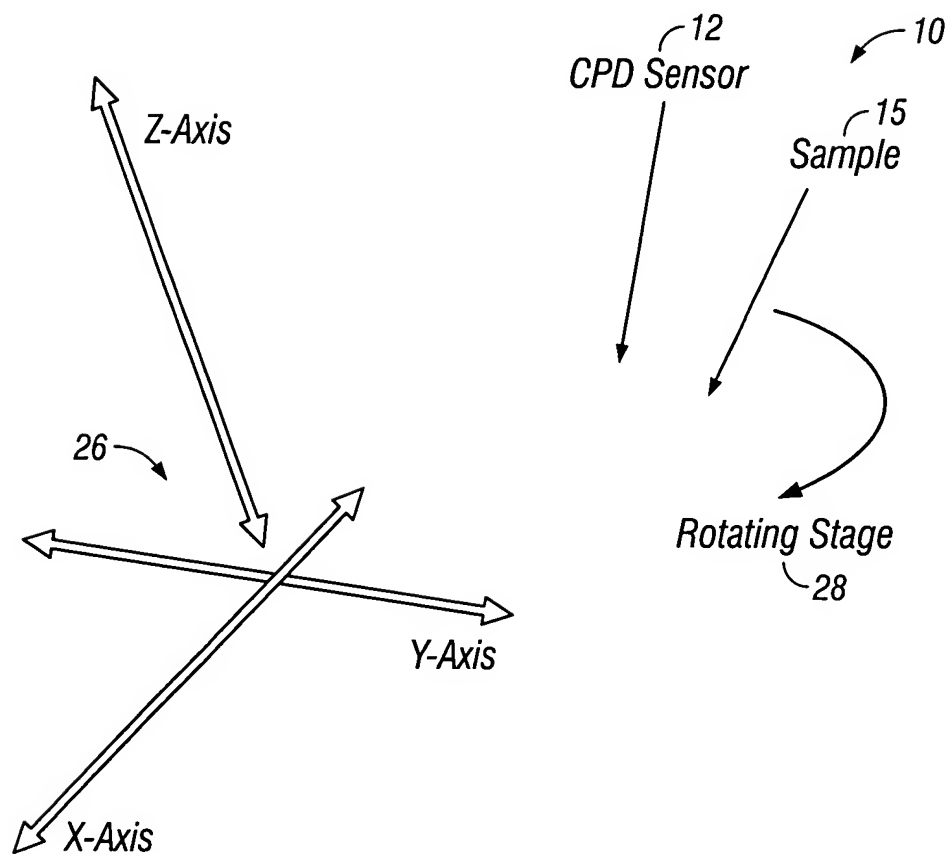
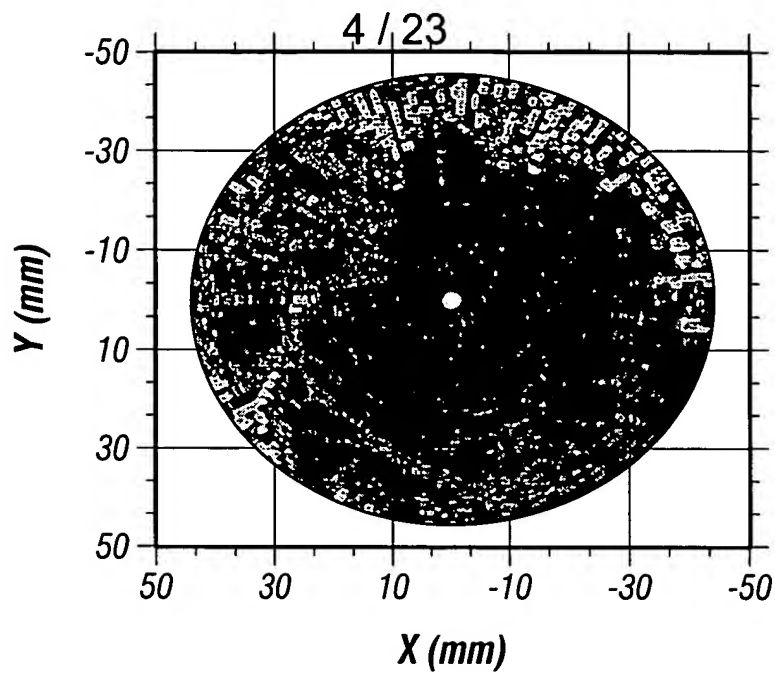
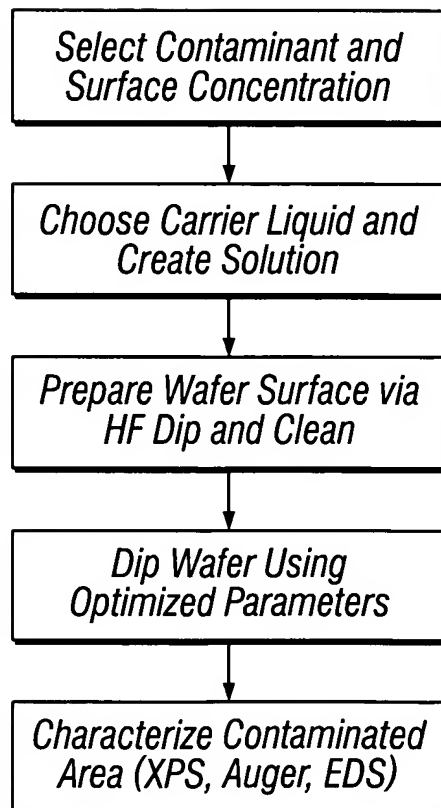


FIG. 5



**FIG. 6**



**FIG. 7**

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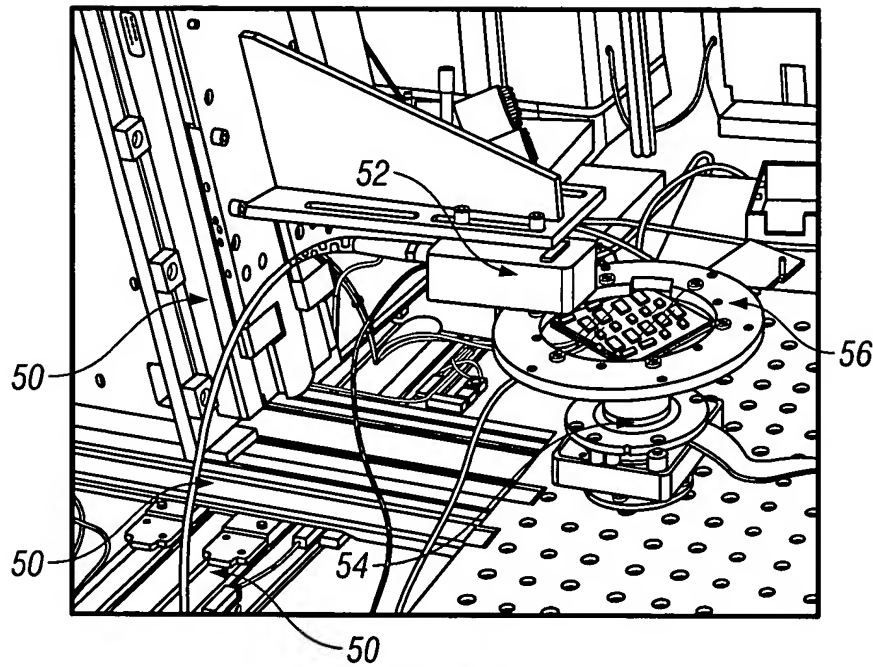
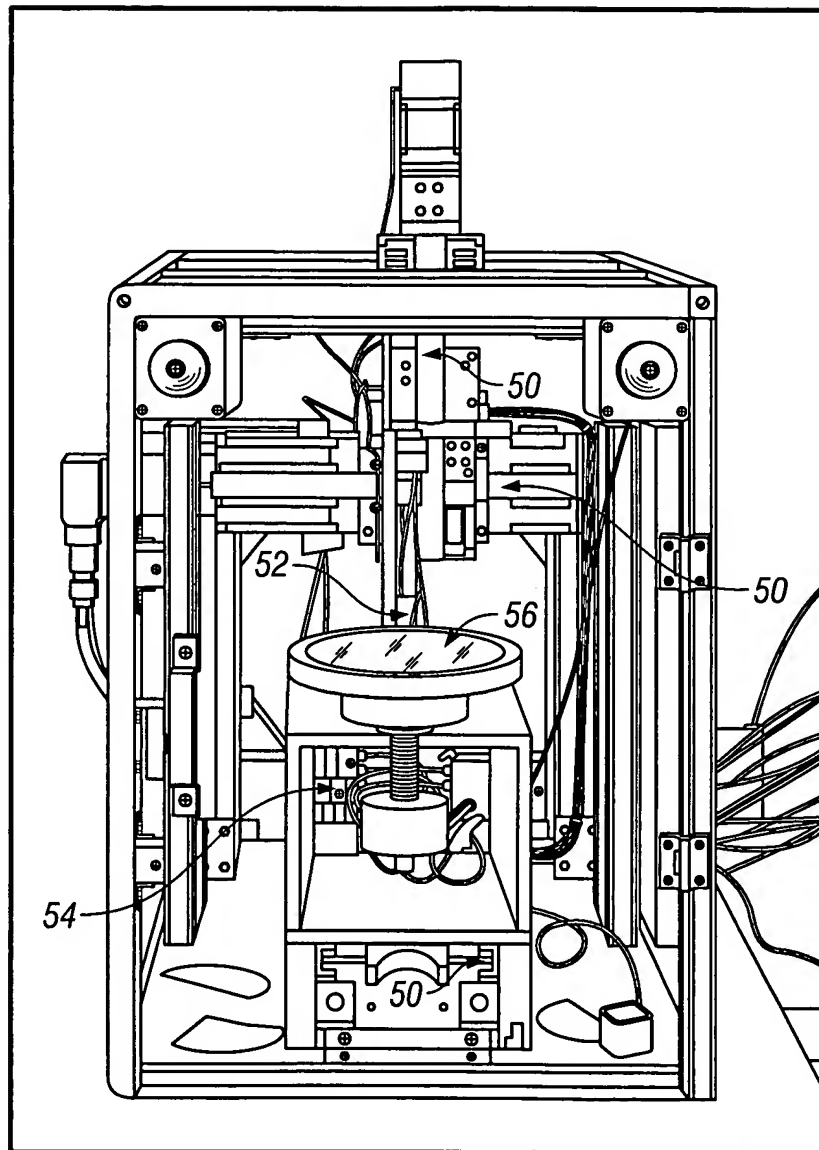


FIG. 8A

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**FIG. 8B**

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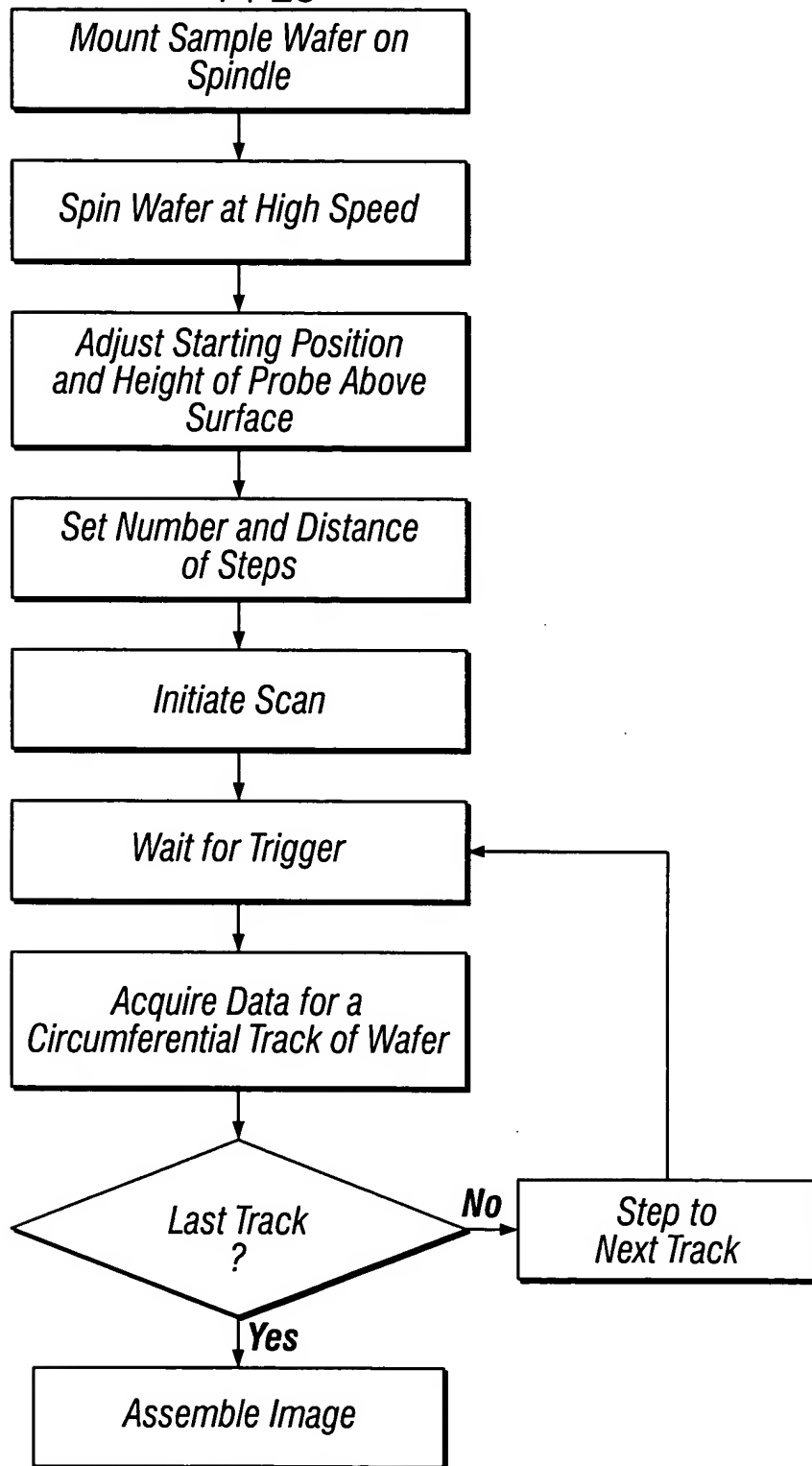


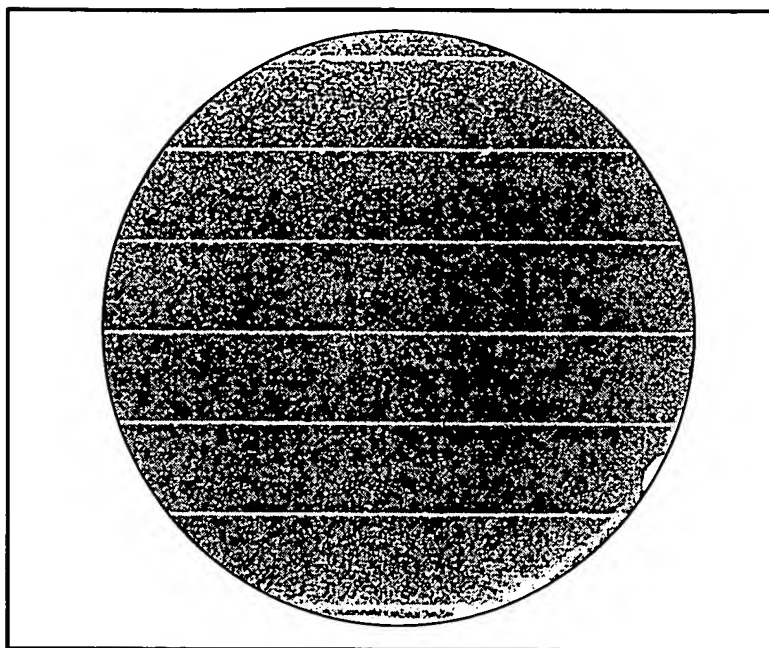
FIG. 9

Title: WAFER INSPECTION SYSTEM

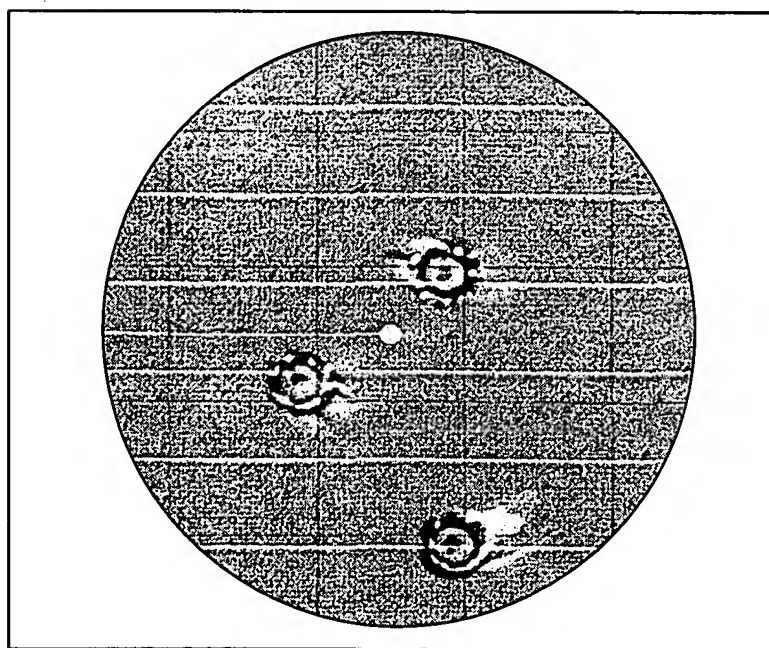
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**FIG. 10A**



**FIG. 10B**

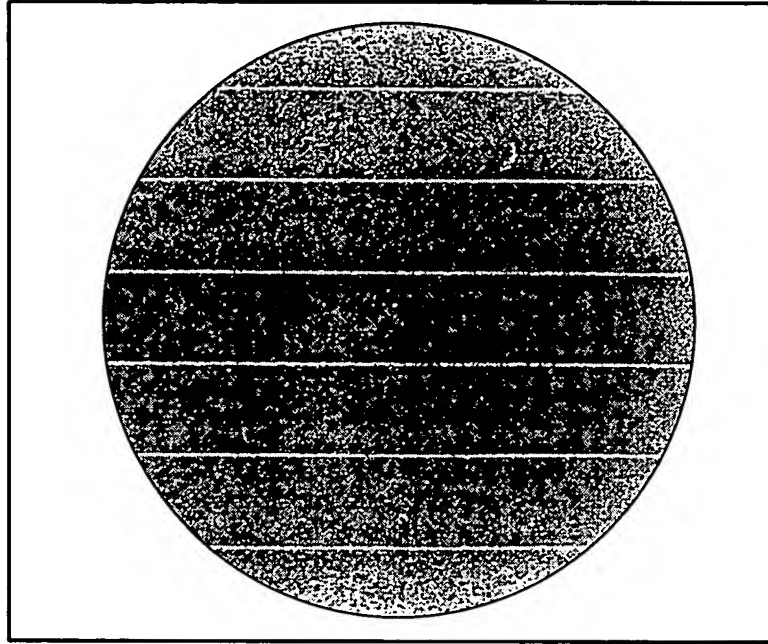


Title: WAFER INSPECTION SYSTEM

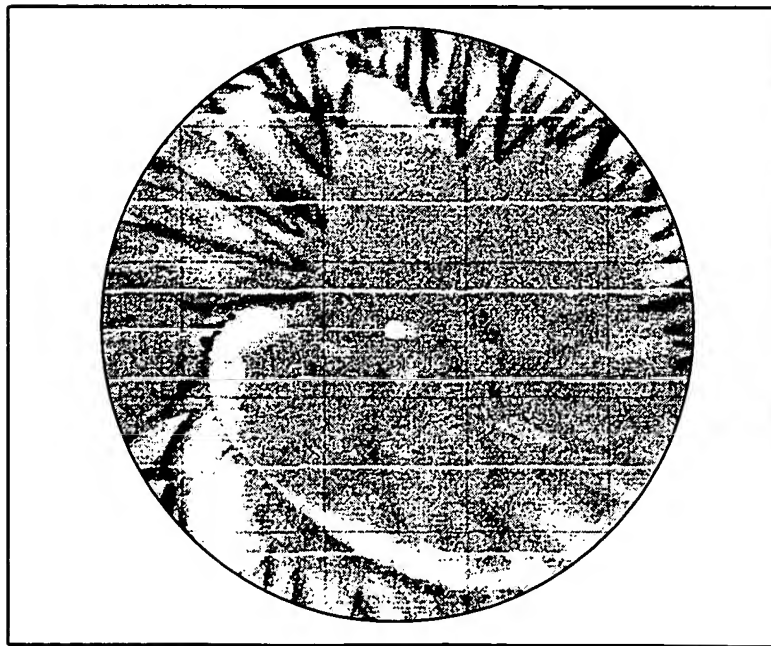
Inventor(s): Steele et al.

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**FIG. 11A**



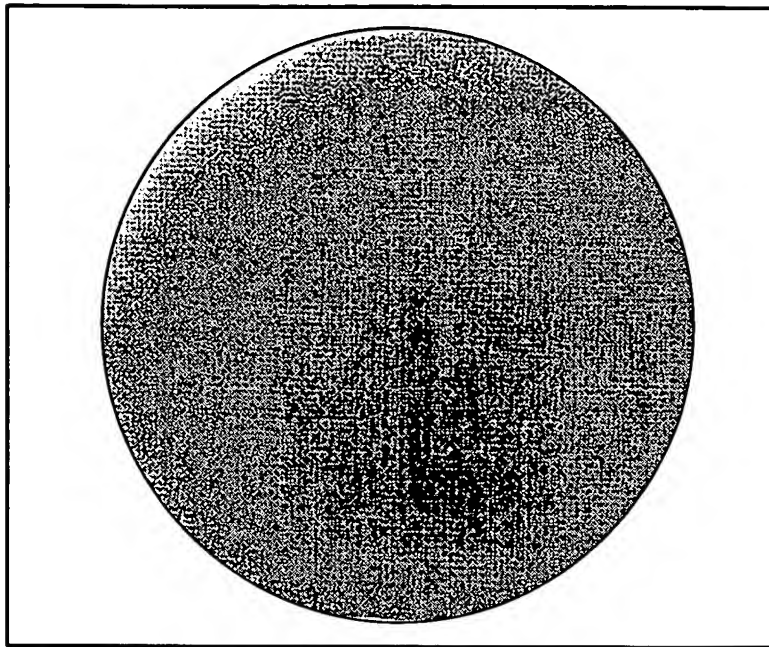
**FIG. 11B**

Title: WAFER INSPECTION SYSTEM

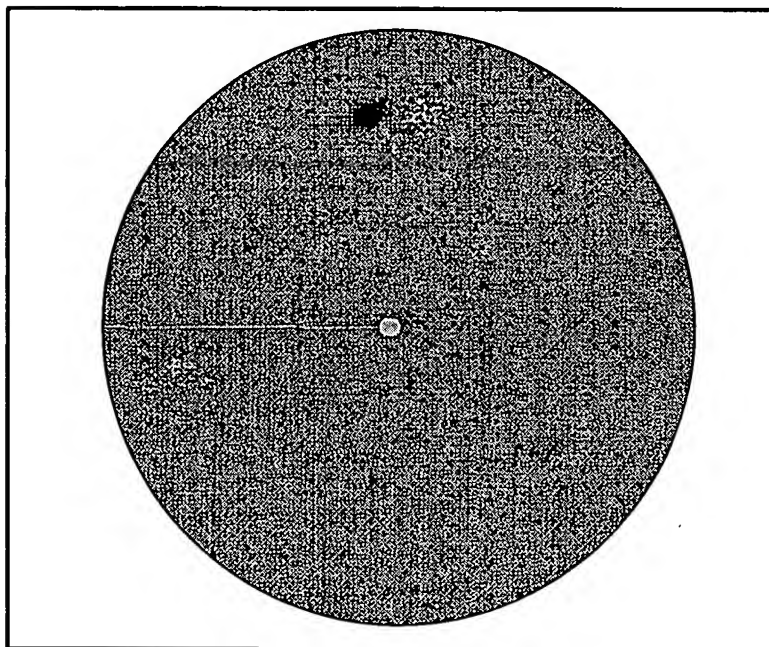
Inventor(s): Steele et al.

Appl. No.: 10/771,628

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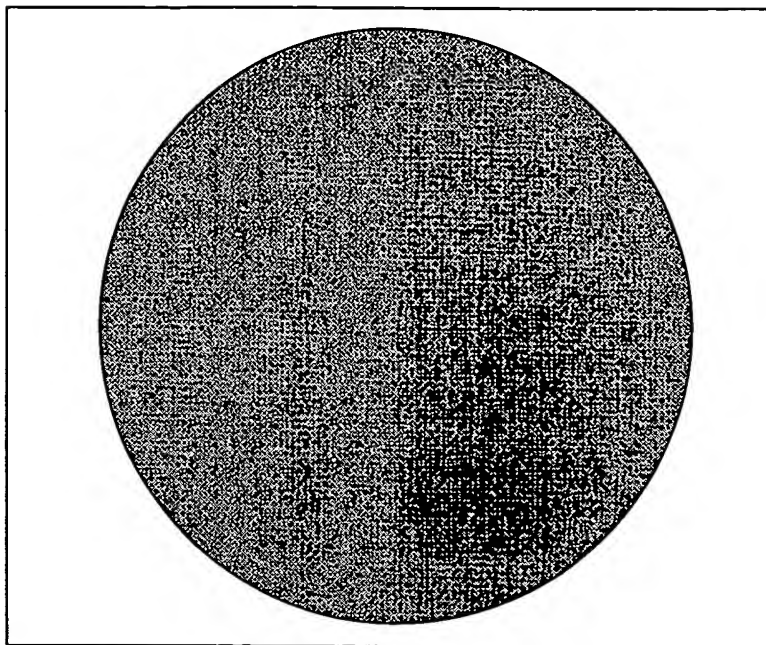


**FIG. 12A**

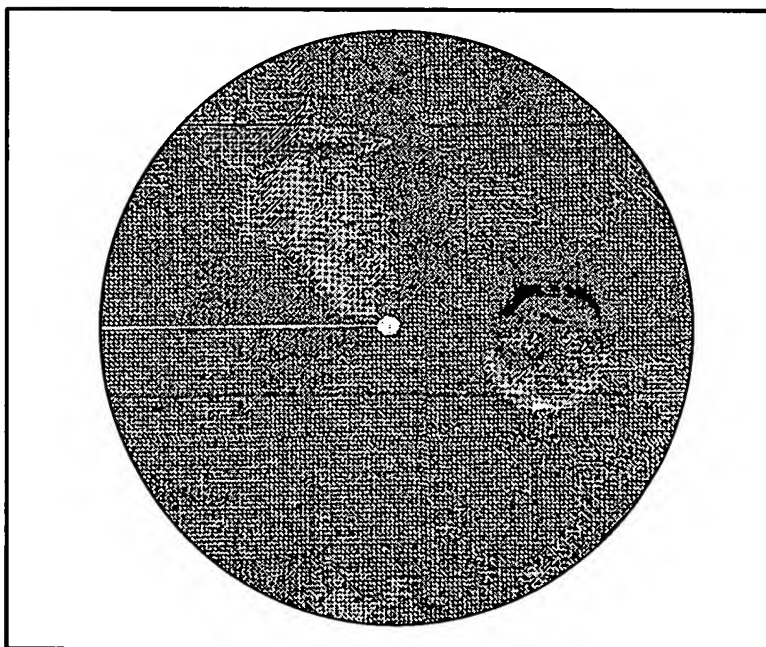


**FIG. 12B**

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**FIG. 13A**



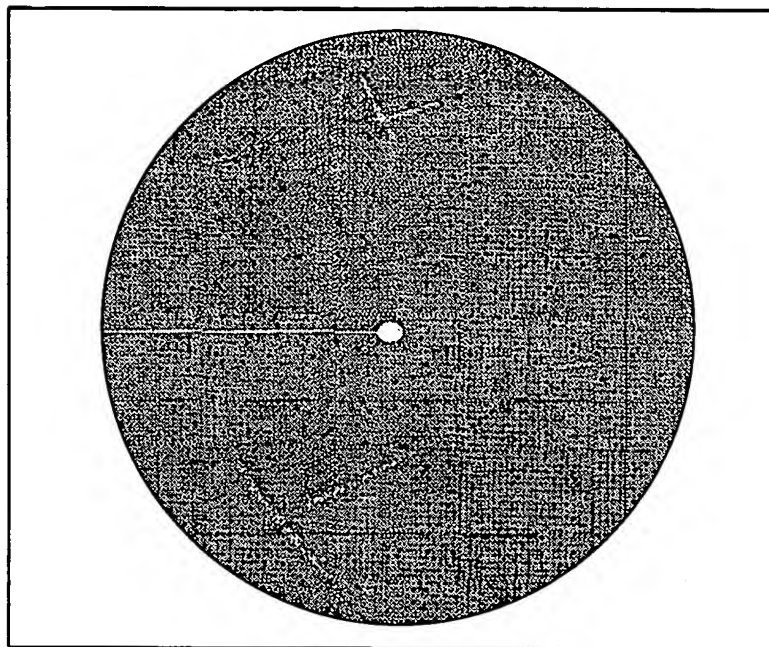
**FIG. 13B**

Title: WAFER INSPECTION SYSTEM

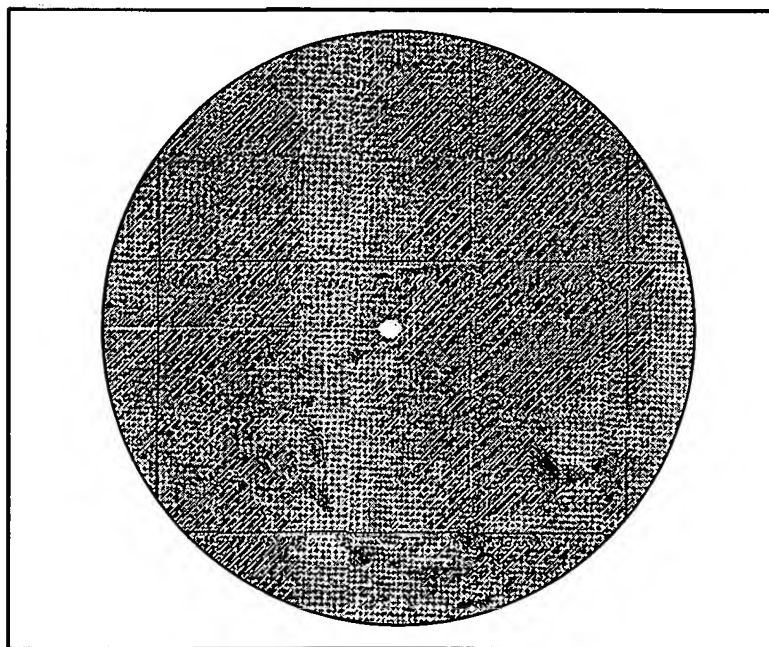
Inventor(s): Steele et al.

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**FIG. 14**



**FIG. 15**

Title: WAFER INSPECTION SYSTEM

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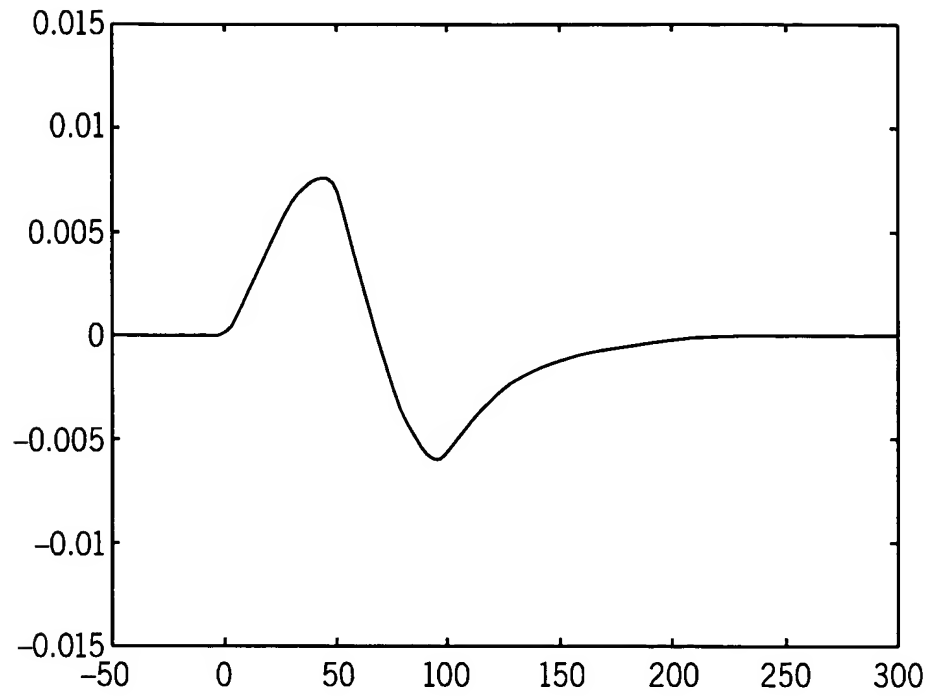


FIG. 16

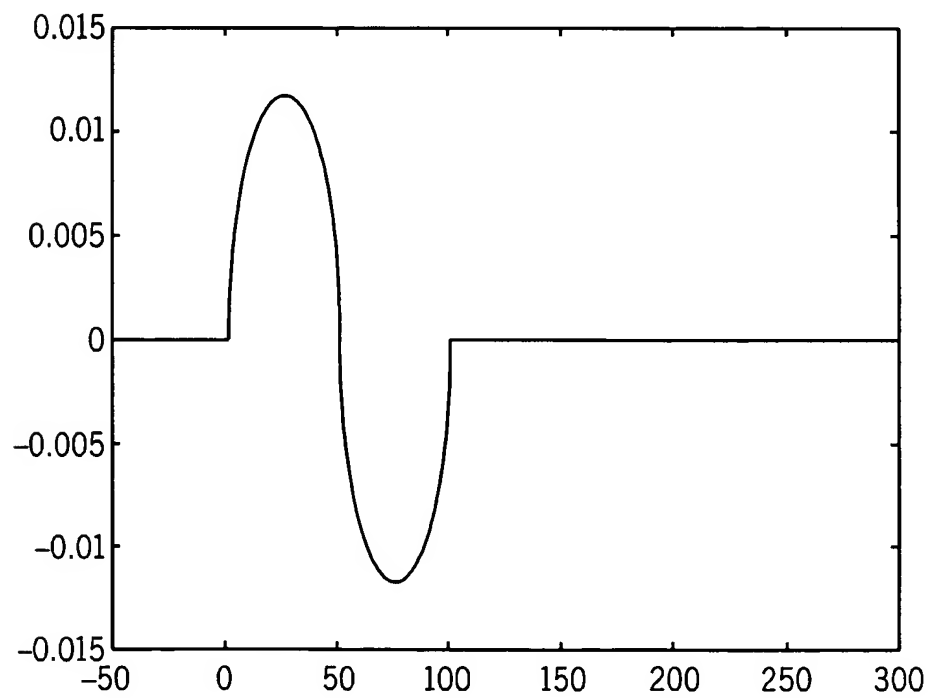


FIG. 17

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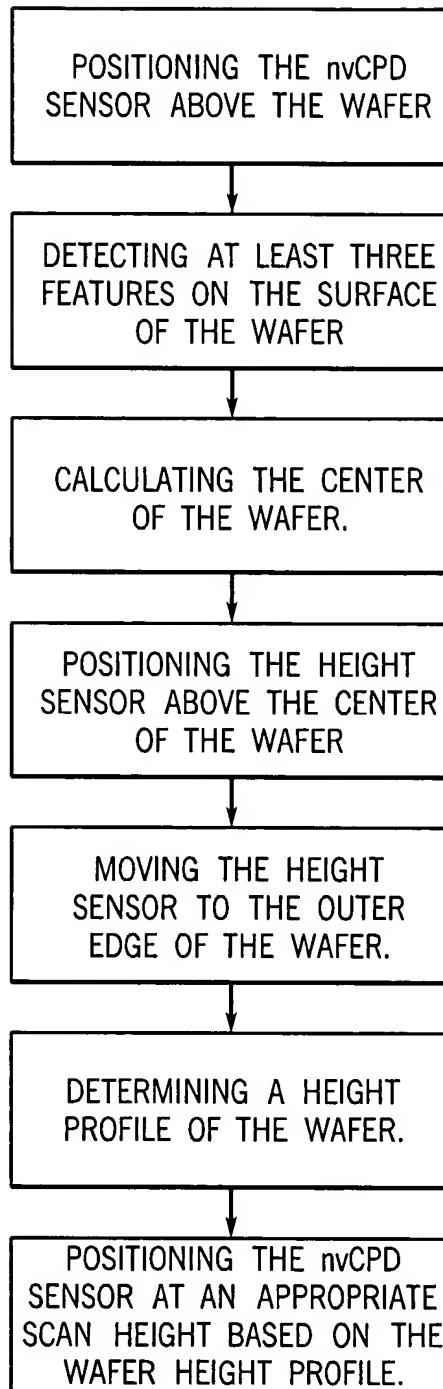


FIG. 18

Title: WAFER INSPECTION SYSTEM

Inventor(s): Steele et al.

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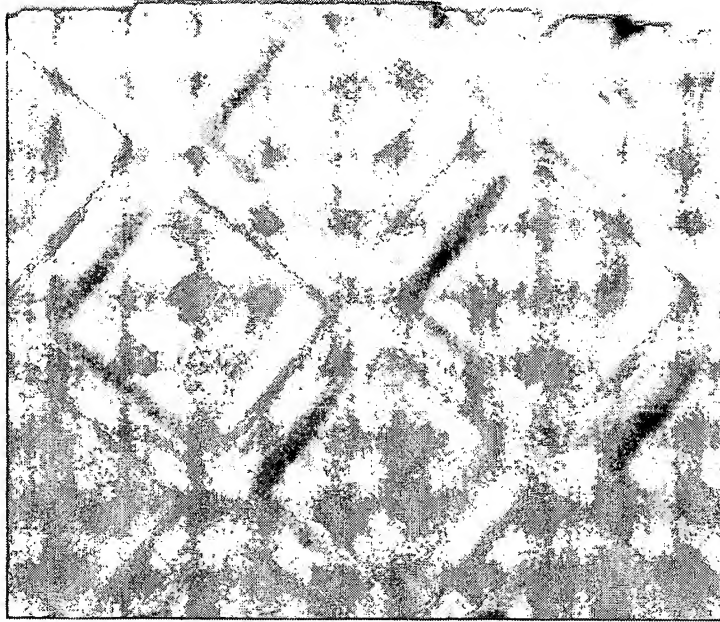


FIG. 19

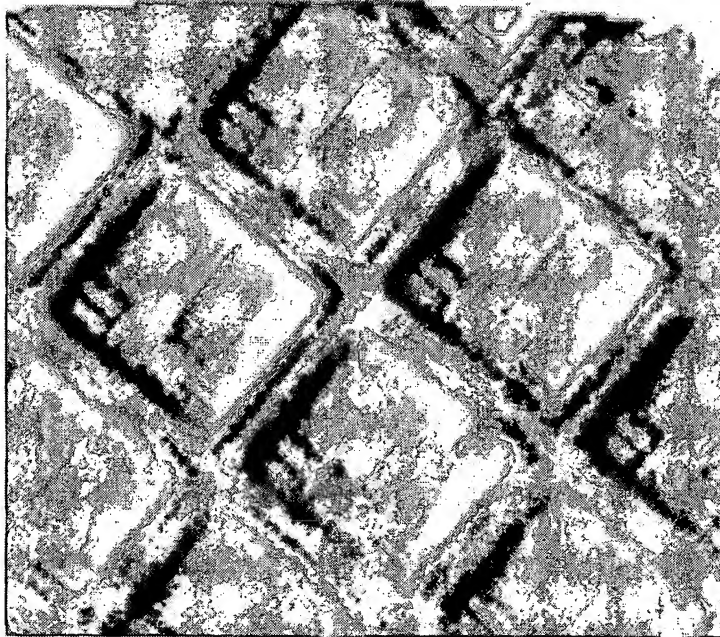


FIG. 20

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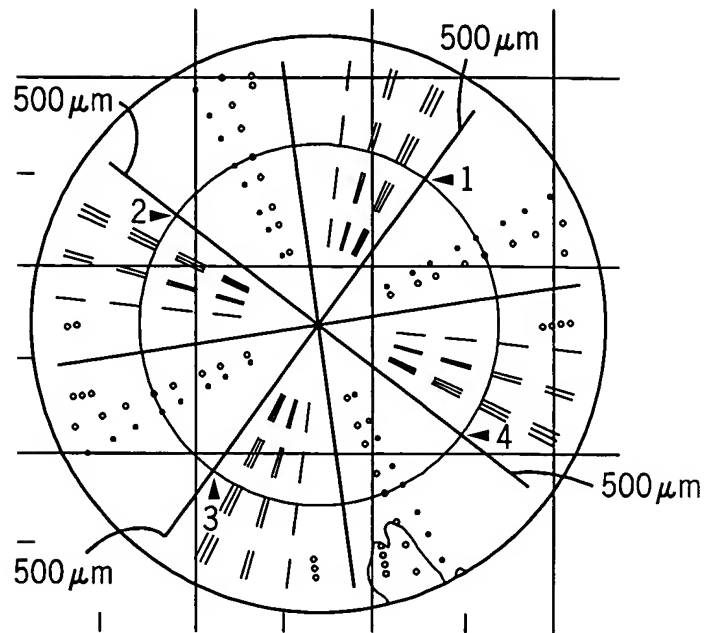


FIG. 21A

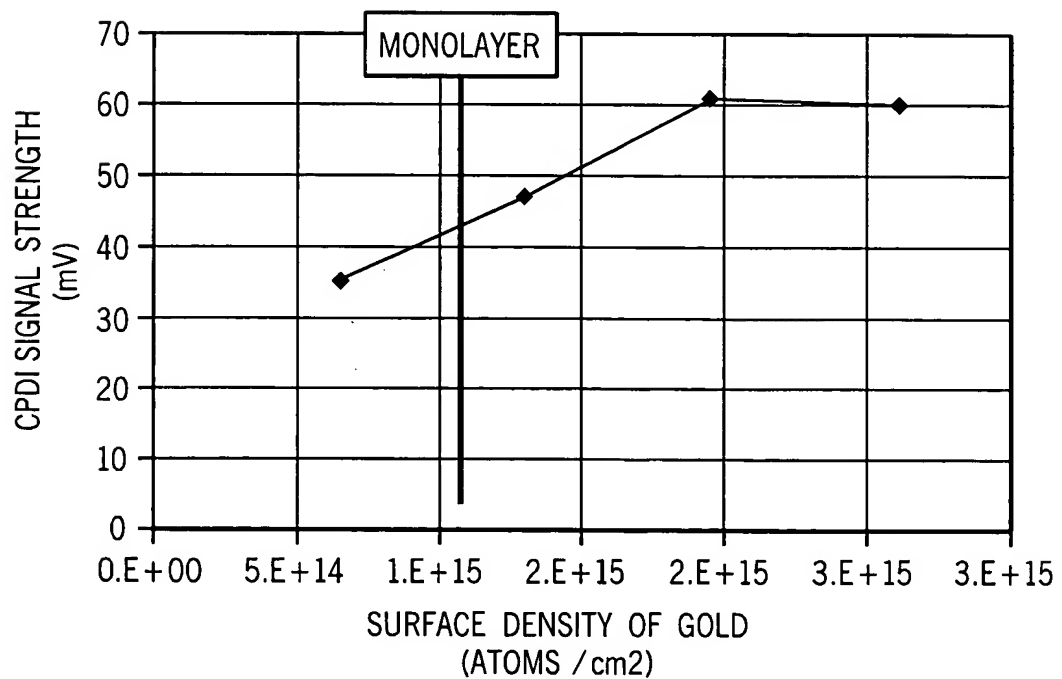


FIG. 21C



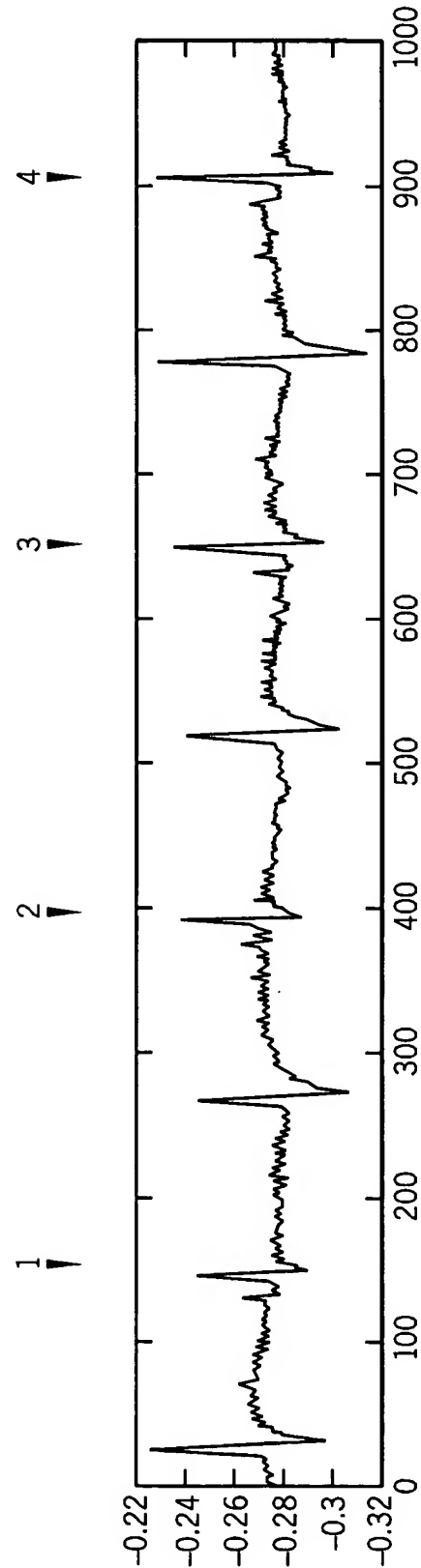


FIG. 21B

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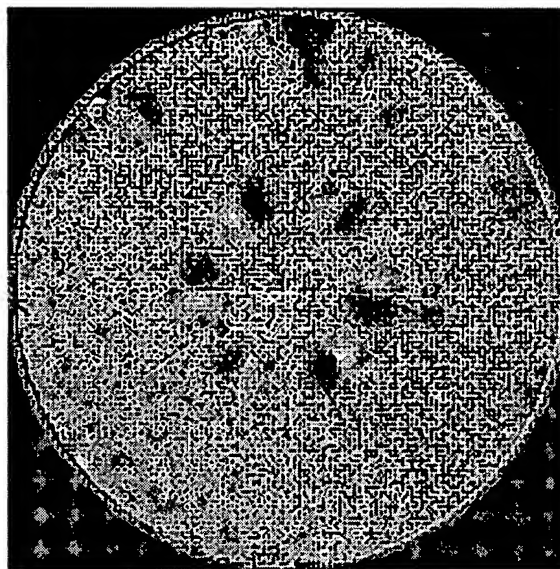


FIG. 22A

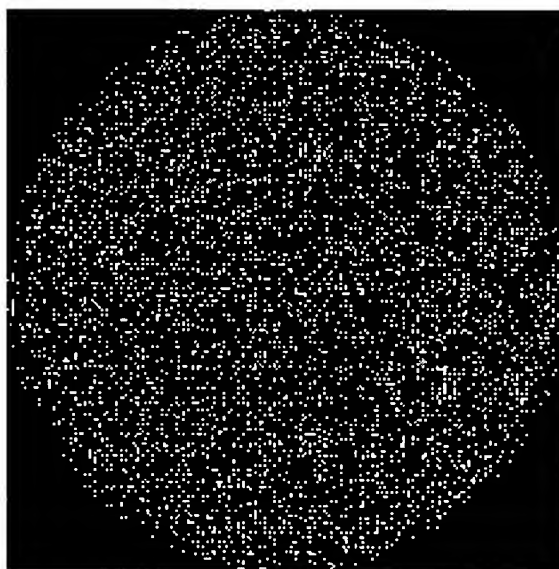


FIG. 22B

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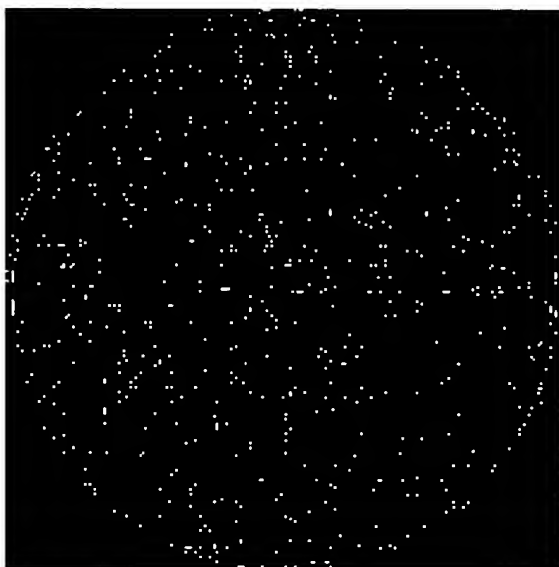


FIG. 22C

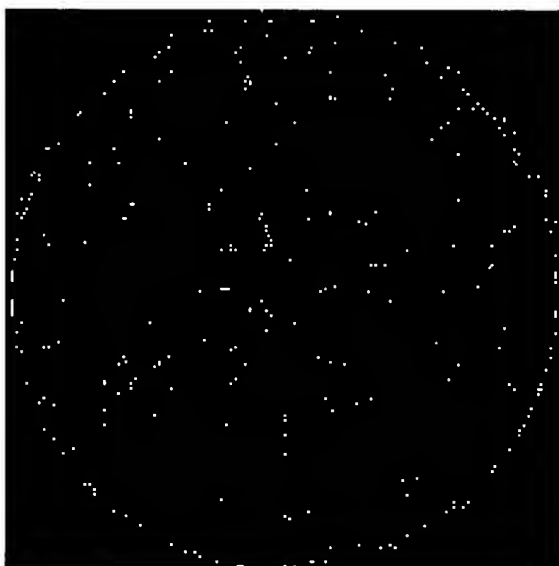


FIG. 22D

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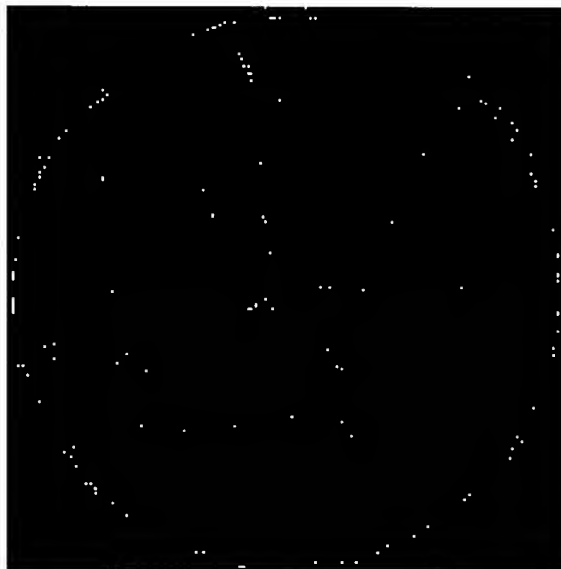


FIG. 22E

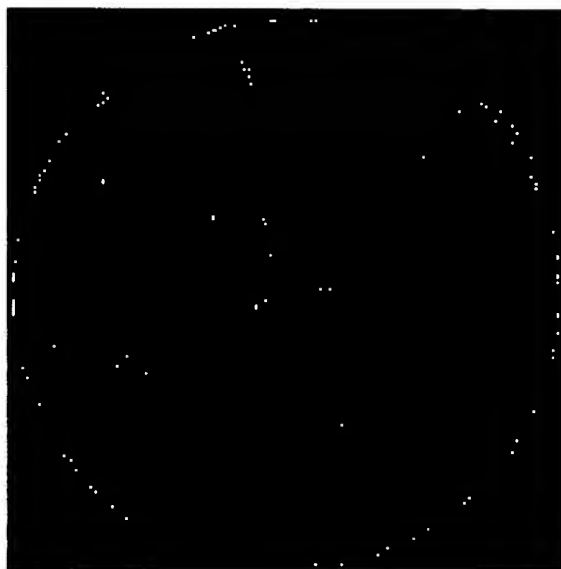


FIG. 22F

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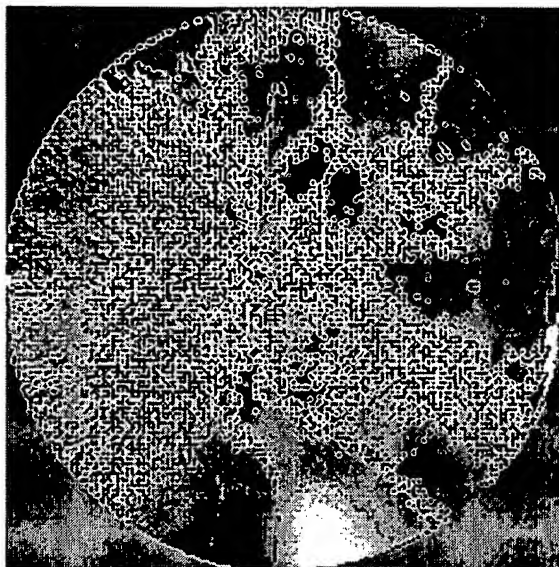


FIG. 23A

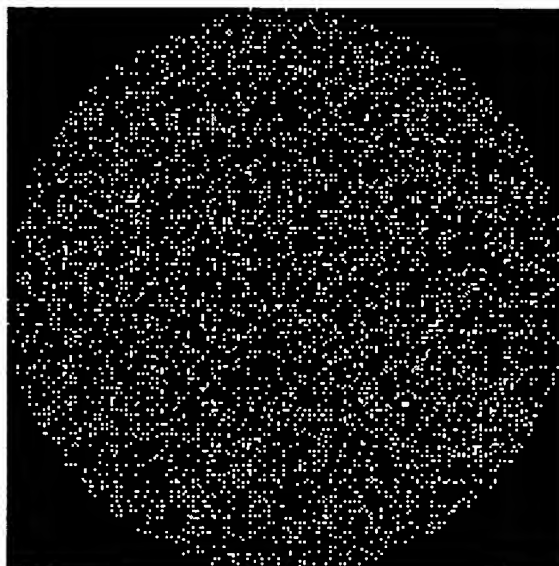


FIG. 23B

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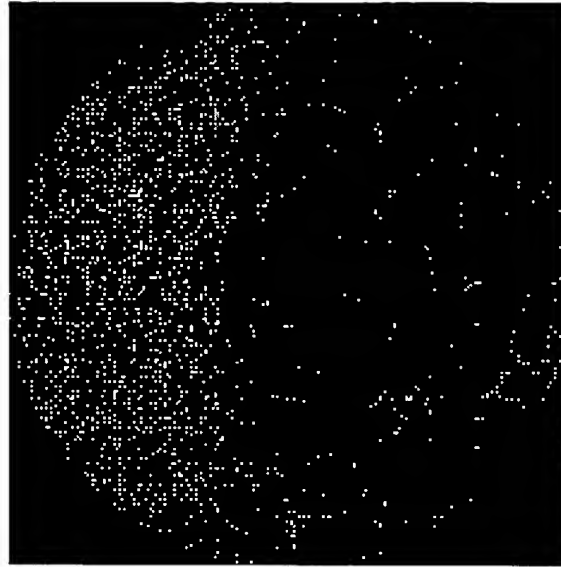


FIG. 23C

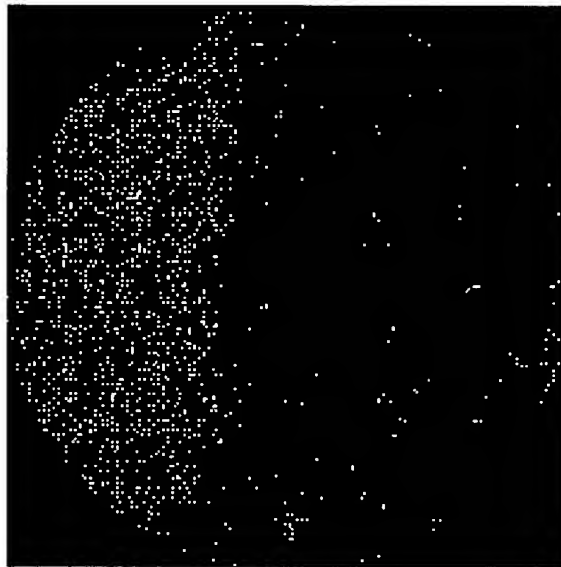


FIG. 23D

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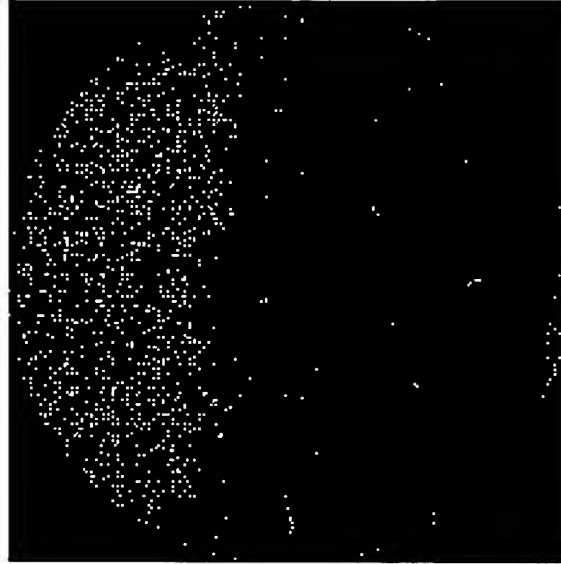


FIG. 23E

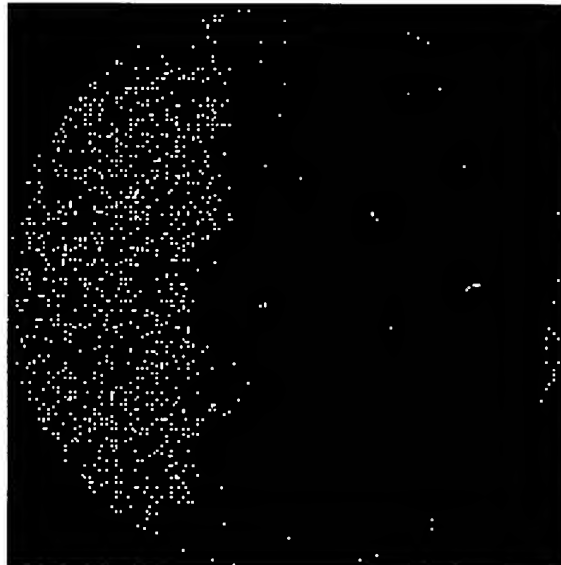


FIG. 23F

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